

## N-Channel MOSFET

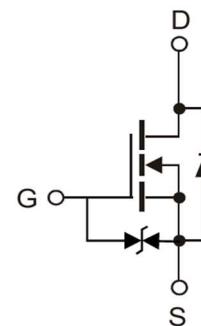
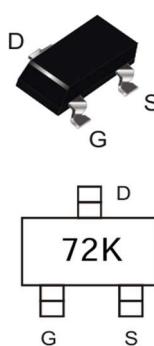
**Features**

- Trench Power MV MOSFET Technology
- Voltage Controlled Small Signal Switch
- Low Input Capacitance
- Halogen-Free & Lead-Free
- ESD Protected up to 2.5KV (HBM)

Product Summary			
V <sub>DS</sub>	R <sub>D(on)</sub> (Ω) Typ	I <sub>D</sub> (mA)	Q <sub>g</sub> (Typ)
60V	1.3 @ 10V	300	1.7nC
	1.4 @ 4.5V	200	

**Application**

- Load Switch for Portable Devices
- Solid-state relays
- Direct logic-level interface: TTL/CMOS

**Marking information**SOT-23

N-channel MOSFET

**Absolute Maximum Ratings (at T<sub>A</sub> = 25°C unless otherwise specified)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	60	V
Gate-Source Voltage (T <sub>A</sub> =25 °C)	V <sub>GS</sub>	±20	V
Continuous drain current (T <sub>A</sub> =25 °C)	I <sub>D</sub>	0.34	A
Continuous drain current (T <sub>A</sub> =70 °C)	I <sub>D</sub>	0.272	A
Peak Drain Current, Pulsed <sup>1)</sup>	I <sub>DM</sub>	1.5	A
Power Dissipation	P <sub>D</sub>	0.35	W
Operating Junction	T <sub>J</sub>	-55~150	°C
Storage Temperature Range	T <sub>stg</sub>	-55~150	°C

**Thermal Characteristics**

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient <sup>2)</sup>	R <sub>θJA</sub>	104	°C/W

**Characteristics at Ta = 25°C unless otherwise specified**

Parameter	Symbol	Min.	Typ.	Max.	Unit
<b>STATIC PARAMETERS</b>					
Drain-Source Breakdown Voltage at V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	BV <sub>DSS</sub>	60			V
Drain-Source Leakage Current at V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	I <sub>DSS</sub>			1	μA
Gate Leakage Current at V <sub>GS</sub> =±5V, V <sub>DS</sub> =0V	I <sub>GSS</sub>			±0.1	μA
Gate-Source Threshold Voltage at V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	V <sub>GS(th)</sub>	1	1.4	2.5	V
Drain-Source On-State Resistance at V <sub>GS</sub> =10V, I <sub>D</sub> =300mA at V <sub>GS</sub> =4.5V, I <sub>D</sub> =200mA	R <sub>DS(on)</sub>		1.3 1.4	2.5 3	Ω
<b>DYNAMIC PARAMETERS</b>					
Input Capacitance at V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz	C <sub>iss</sub>		18		pF
Output Capacitance at V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz	C <sub>oss</sub>		12		pF
Reverse Transfer Capacitance at V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz	C <sub>rss</sub>		7		pF
Gate charge total at V <sub>DS</sub> =30V, I <sub>D</sub> =0.3A, V <sub>GS</sub> =10V	Q <sub>g</sub>		1.7	2.4	nC
Turn-On Delay Time at V <sub>DD</sub> =30V, I <sub>D</sub> =0.3A, R <sub>GEN</sub> =6Ω, V <sub>GS</sub> =10V	t <sub>d(on)</sub>		5		nS
Turn-Off Delay Time at V <sub>DD</sub> =30V, I <sub>D</sub> =0.3A, R <sub>GEN</sub> =6Ω, V <sub>GS</sub> =10V	t <sub>d(off)</sub>		17		nS
<b>Body-Diode PARAMETERS</b>					
Drain-Source Diode Forward Voltage at I <sub>S</sub> =0.3A, V <sub>GS</sub> =0V	V <sub>SD</sub>			1.2	V
Maximum Body-Diode Continuous Current	I <sub>S</sub>			340	mA
Body Diode Reverse Recovery Time at V <sub>R</sub> =25V, V <sub>GS</sub> =0V I <sub>S</sub> =0.3A, di/dt=100A/μs	trr		30		nS

Note:

- 1) Pulse Test: Pulse width≤300us, Duty cycle ≤2%.
- 2) Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

## Electrical Characteristics Curves

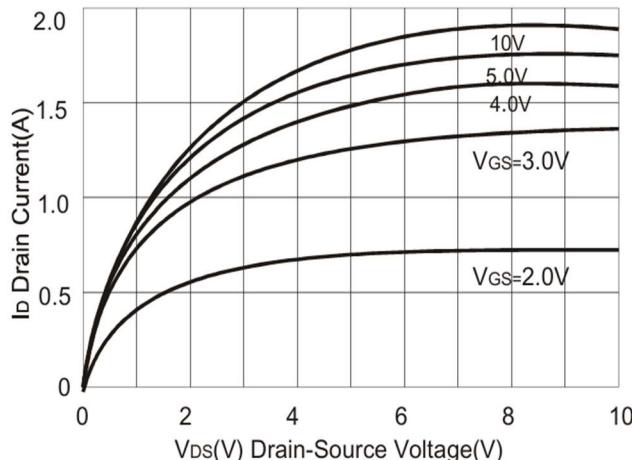


Fig1. Output Characteristics

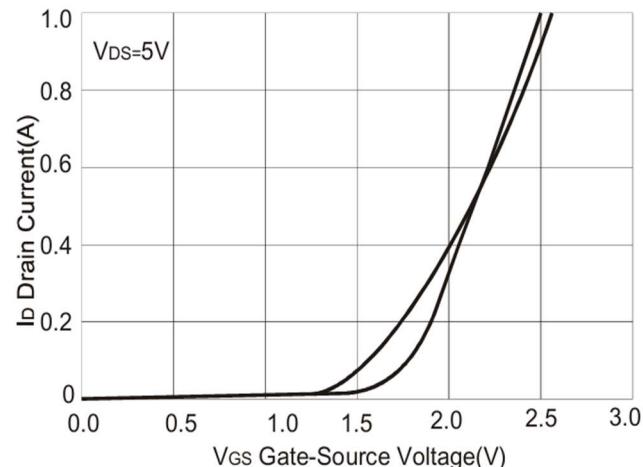


Fig2. Transfer Characteristics

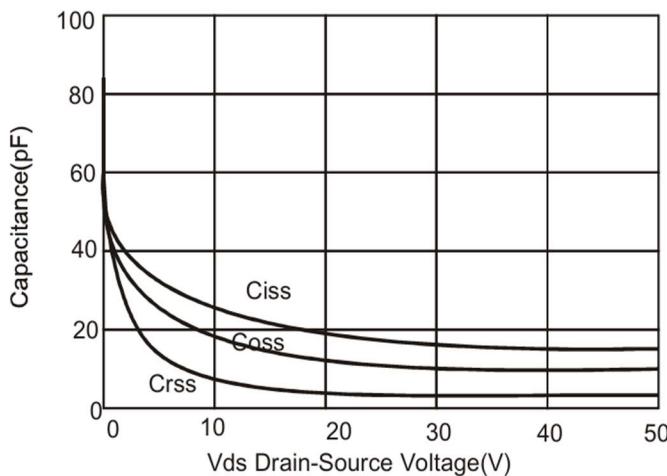


Fig3. Capacitance Characteristics

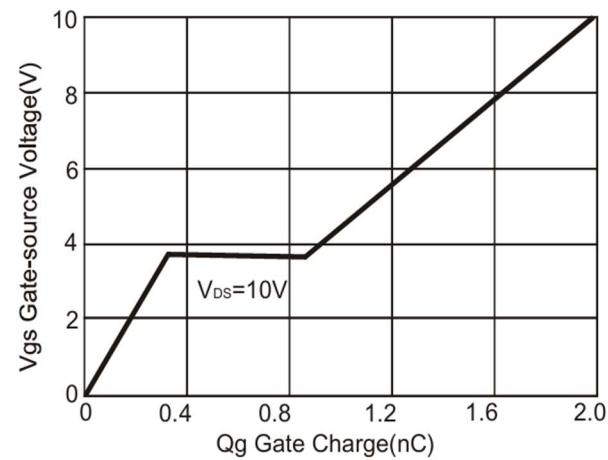


Fig4. Gate Charge

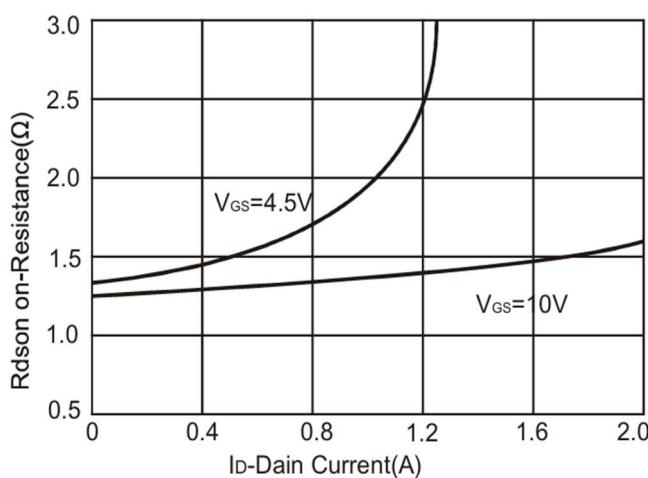


Fig5. Drain-Source on Resistance

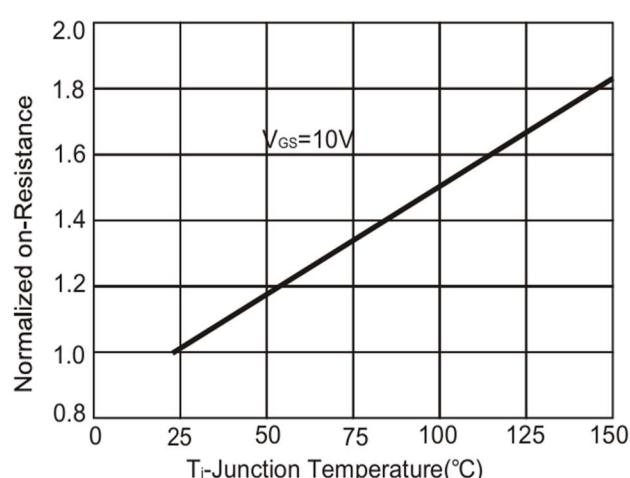


Fig6. Drain-Source on Resistance

## Electrical Characteristics Curves

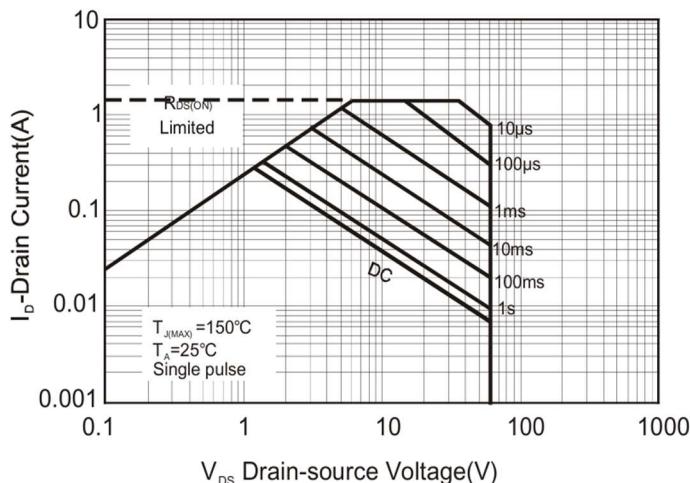


Fig7. Safe Operation Area

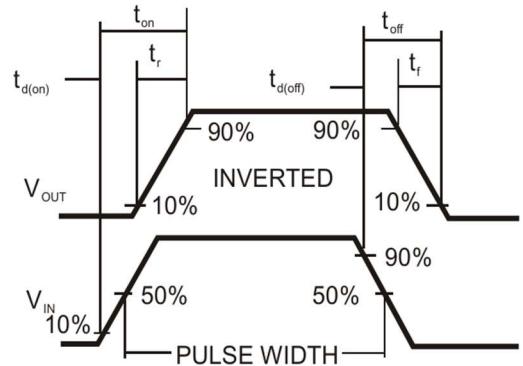
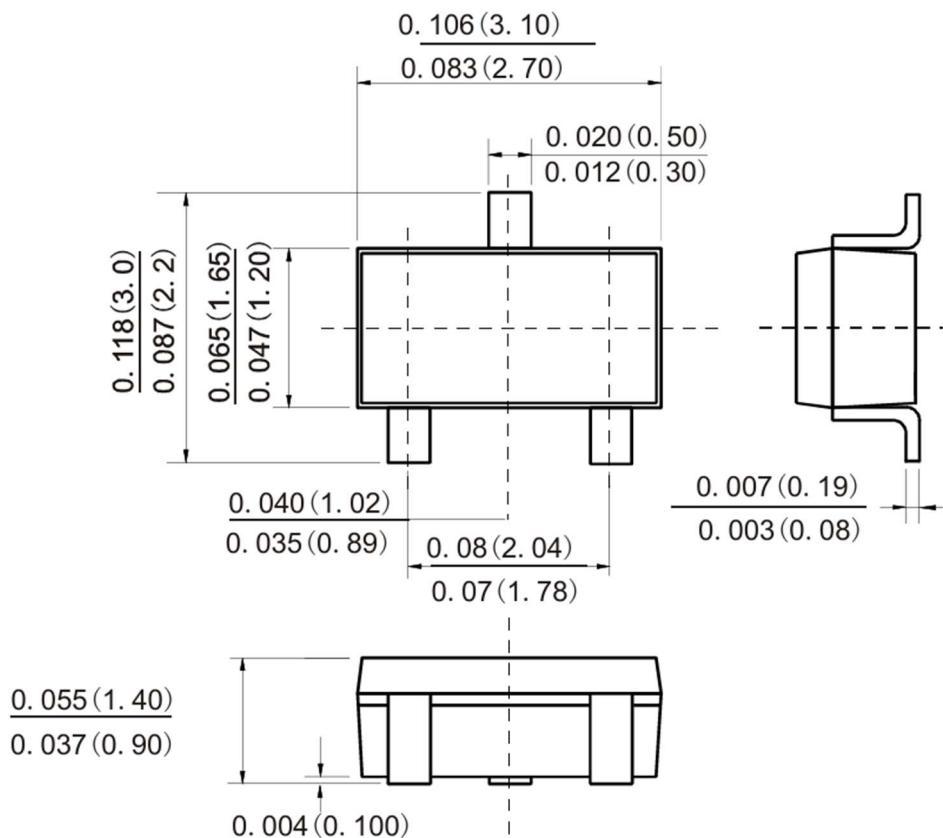
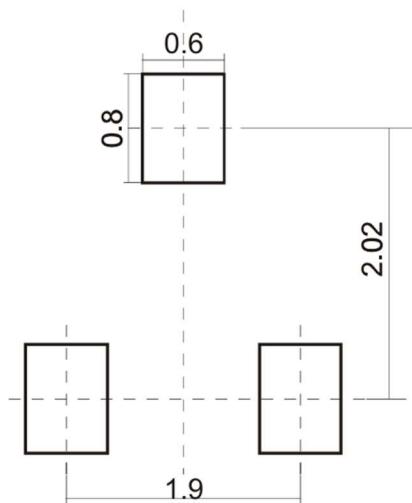


Fig8. Switching wave

## Package Outline Dimensions (Units: mm) SOT-23



Dimensions in inches and (millimetres)

**Suggested Pad Layout**

Dimensions in millimetres

**Order Information**

Part Number	Package	Quantity
Sh2N7002K	SOT-23	3000